

#### **General Description**

This PAN40S48Y N-Channel enhancement mode power field effect transistor is the high density trench technology and this advanced technology can provide excellent Rds(On) performance and efficiency for power switching and load switching application., this device also comply with the RoHS and Green Product requirement with full function reliability approved.

| BVDSS | RDSON | ID   |
|-------|-------|------|
| 40V   | 1.8mΩ | 100A |

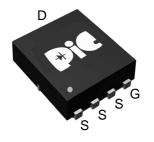
#### Feature

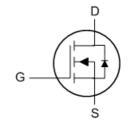
- ◆ Super Low Gate Charge
- ◆ 100% EAS Guaranteed
- ◆ Green Device Available
- ◆ Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

#### **Application**

- ▼ DC/DC Primary Side Switche
- ▼ Industrial Synchronous
- ▼ RectificationeLoad Switch
- ▼ DC/DC Converters

### **DNF5X6A-EP1 Pin Configuration**





#### **Absolute Maximum Ratings**

| Parameter  | Symbol      | Rating     | Units |
|--|-------------|------------|-------|
| Drain-Source Voltage                               | Vos         | 40         | V     |
| Gate-Source Voltage                                | Vgs         | ±20        | V     |
| Continuous Drain Current, Vgs @ 10V <sub>1,6</sub> | Ip@Tc=25°C  | 100        | А     |
| Continuous Drain Current, Vgs @ 10V <sub>1,6</sub> | In@Tc=100°C | 82         | А     |
| Pulsed Drain Current <sub>2</sub>                  | Ідм         | 400        | А     |
| Single Pulse Avalanche Energy <sub>3</sub>         | EAS         | 400        | mJ    |
| Avalanche Current                                  | las         | 40         | А     |
| Total Power Dissipation₄                           | Pp@Tc=25°C  | 125        | W     |
| Storage Temperature Range                          | Тѕтс        | -55 to 150 | °C    |
| Operating Junction Temperature Range               | TJ          | -55 to 150 | ℃     |
| Thermal Resistance Junction-Ambient 1              | Reja        | 50         | °C/W  |
| Thermal Resistance Junction-Case <sub>1</sub>      | Reuc        | 1          | °C/W  |



### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

| Parameter                            | Symbol             | Conditions  | Min. | Тур. | Max. | Unit   |  |
|--------------------------------------|--------------------|---|------|------|------|--------|--|
| Drain-Source Breakdown Voltage       | BVDSS              | Vgs=0V , Ip=250uA   | 40   |      |      | V      |  |
| Static Drain-Source OnResistance2    | RDS(ON)            | Vgs=10V, ID=20A   |      | 1.5  | 1.8  | mΩ     |  |
| Static Dialii-Source Officesistance2 | KDS(ON)            | Vgs=4.5V, ID=20A  |      | 2.0  | 2.6  | 1115.2 |  |
| Gate Threshold Voltage               | VGS(th)            | Vgs=Vps , Ip =250uA   | 1.2  | 1.6  | 2.2  | V      |  |
| Drain Source Leakage Current         | Ipss               | V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C |      |      | 1    | 1 uA   |  |
| Drain-Source Leakage Current         | IDSS               | V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C |      |      | 5    |        |  |
| Gate-Source Leakage Current          | Igss               | Vgs=±20V, Vps=0V  |      |      | ±100 | nA     |  |
| Forward Transconductance             | gfs                | V <sub>DS</sub> =5V , I <sub>D</sub> =20A                         |      | 53   |      | S      |  |
| Gate Resistance                      | Rg                 | V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz                |      | 1.0  |      | Ω      |  |
| Total Gate Charge (4.5V)             | Qg                 |   |      | 45   |      | nC     |  |
| Gate-Source Charge                   | Qgs                | Vps=15V , Vgs=10V , Ip=20A  |      | 12   |      |        |  |
| Gate-Drain Charge                    | Qgd                |   |      | 18.5 |      |        |  |
| Turn-On Delay Time                   | T <sub>d(on)</sub> |   |      | 18.5 |      |        |  |
| Rise Time                            | Tr                 | $V_{DD}$ =15 $V$ , $V_{GS}$ =10 $V$ , $R_{G}$ =3.3 $\Omega$ ,     |      | 9    |      | ns ns  |  |
| Turn-Off Delay Time                  | Td(off)            | ID=20A  |      | 58.5 |      |        |  |
| Fall Time                            | Tf                 |   |      | 32   |      |        |  |
| Input Capacitance                    | Ciss               |   |      | 3972 |      |        |  |
| Output Capacitance                   | Coss               | Vps=20V , Vgs=0V , f=1MHz   |      | 1119 |      | pF     |  |
| Reverse Transfer Capacitance         | Crss               |   |      | 82   |      |        |  |

#### **Diode Characteristics**

| Parameter                                | Symbol | Conditions              | Min. | Тур. | Max. | Unit |
|--|--------|-------------------------|------|------|------|------|
| Continuous Source Current <sub>1,6</sub> | ls     | Vg=VD=0V, Force Current |      |      | 100  | Α    |
| Diode Forward Voltage <sub>2</sub>       | VsD    | Vgs=0V , Is=1A , TJ=25℃ |      |      | 1.2  | V    |

#### Note:

- 1. Pulse width limited by maximum junction temperature.
- 2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.5mH,  $I_{AS}$ =40A
- 4.Ensure that the channel temperature does not exceed 150°C.
- 5. The data is theoretically the same as ID and IDM, in real applications, should be limited by total power dissipation.
- 6.Package limitation current is 100A.



## **Typical Characteristics**

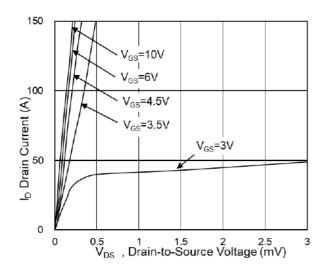


Fig.1 Typical Output Characteristics

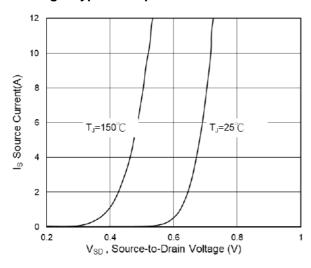


Fig.3 Source Drain Forward Characteristics

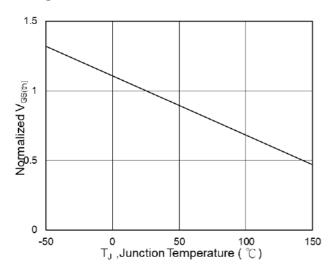


Fig.5 Normalized  $V_{\text{GS(th)}}$  vs  $T_{\text{J}}$ 

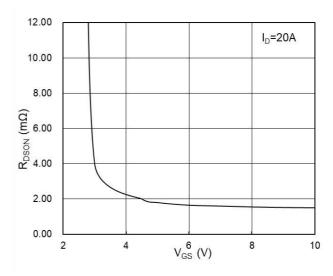
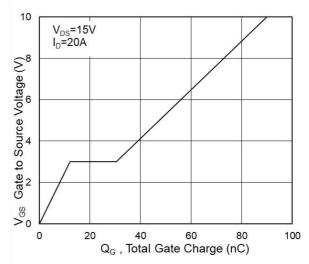


Fig.2 On-Resistance vs G-S Voltage



**Fig.4 Gate-Charge Characteristics** 

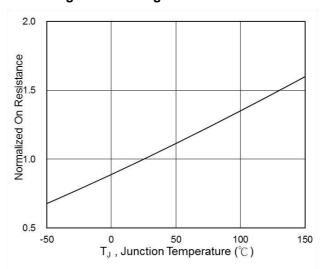
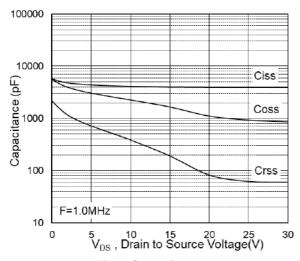


Fig.6 Normalized R<sub>DSON</sub> vs T<sub>J</sub>





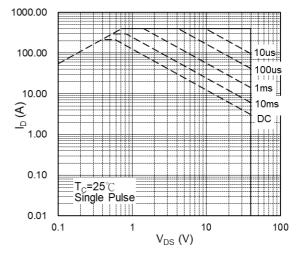


Fig.7 Capacitance

Fig.8 Safe Operating Area

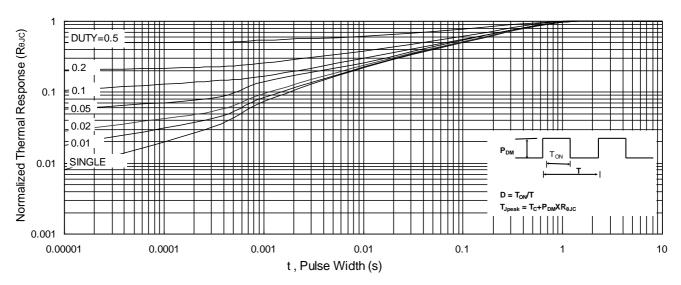


Fig.9 Normalized Maximum Transient Thermal Impedance

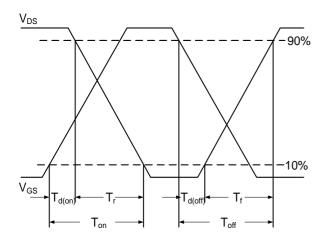
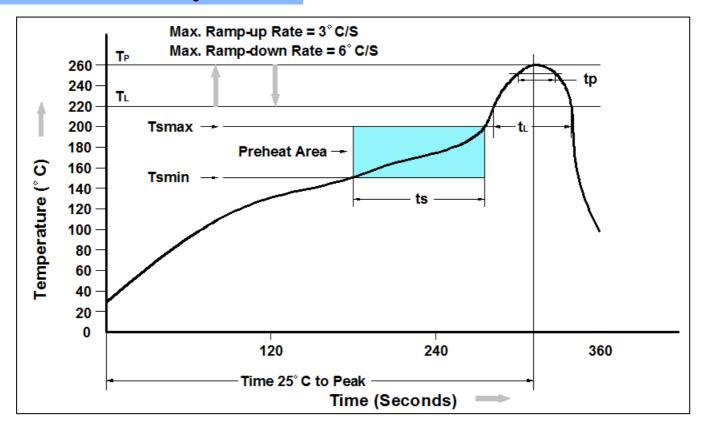


Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform



### Recommand IR Reflow Soldering Thermal Profile



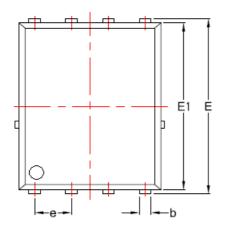
| Profile Feature                                 | Pb-Free Assembly Profile |  |  |
|---|--------------------------|--|--|
| Temperature Min. (Tsmin)                        | 150°C                    |  |  |
| Temperature Max. (Tsmax)                        | 200°C                    |  |  |
| Time (ts) from (Tsmin to Tsmax)                 | 60-120 seconds           |  |  |
| Average Ramp-up Rate (tLto tP)                  | 3°C/second max.          |  |  |
| Liquidous Temperature (TL)                      | 217°C                    |  |  |
| Time (tL) Maintained Above (TL)                 | 60 – 150 seconds         |  |  |
| Peak Temperature                                | 260°C +0°C / -5°C        |  |  |
| Time (tP) within 5°C of actual Peak Temperature | 30 seconds               |  |  |
| Ramp-down Rate (TP to TL)                       | 6°C/second max           |  |  |
| Time 25°C to Peak Temperature                   | 8 minutes max.           |  |  |

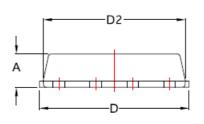
### **Ordering Information**

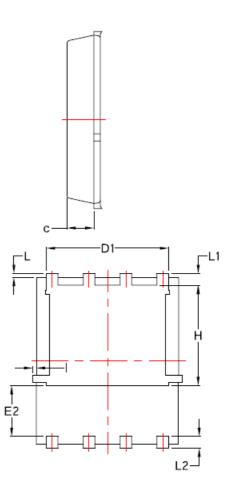
| Part Number | Description      | Quantity |
|-------------|------------------|----------|
| PAN40S48Y   | DFN5X6A-EP1 Reel | 3000 pcs |



## Package Information (DFN5X6A-EP1)







| CVMDOLC | MILLIMETERS |       | INCH     | HES    |  |
|---------|-------------|-------|----------|--------|--|
| SYMBOLS | MIN         | MAX   | MIN      | MAX    |  |
| А       | 1.03        | 1.17  | 0.0406   | 0.0461 |  |
| b       | 0.34        | 0.48  | 0.0134   | 0.0189 |  |
| С       | 0.824       | 0.970 | 0.0324   | 0.0382 |  |
| D       | 4.80        | 5.40  | 0.1890   | 0.2126 |  |
| D1      | 4.11        | 4.31  | 0.1618   | 0.1697 |  |
| D2      | 4.80        | 5.00  | 0.1890   | 0.1969 |  |
| I       |             | 0.18  |          | 0.0070 |  |
| Е       | 5.90        | 6.15  | 0.2323   | 0.2421 |  |
| E1      | 5.65        | 5.85  | 0.2224   | 0.2303 |  |
| E2      | 1.10        |       | 0.0433   |        |  |
| е       | 1.27        | BSC   | 0.05 BSC |        |  |
| Н       | 3.30        | 3.78  | 0.1299   | 0.1488 |  |
| L       | 0.05        | 0.25  | 0.0020   | 0.0098 |  |
| L1      | 0.38        | 0.61  | 0.0150   | 0.0240 |  |
| L2      | 0.38        | 0.71  | 0.0150   | 0.0279 |  |





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